



TEF 2026: The AI Future: Ethernet

7 - 8 October 2026
Hyatt Centric | Mountain View, CA

Call for Presentations

AI networks aren't just moving toward Ethernet — they're converging on it at every layer of scale. Scale-up, scale-out, scale-across... wherever AI architectures are expanding, Ethernet is winning the battle.

And the market signals are unmistakable. Industry analysts now project that cumulative Ethernet switching spend over the next five years will surge past trillions of dollars. Not because demand is uncertain — but because demand is so intense that supply may be the only limiting factor. Sustaining this trajectory requires more than momentum. It demands continued development of robust, interoperable Ethernet standards capable of supporting AI's next wave of scale, complexity, and performance.

IEEE 802.3 has already begun work on 400 Gb/s electrical and optical signaling, but the exploration cannot stop there. The Ethernet Alliance invites the community to help shape what comes next. Your insights, research, and innovations will help define the standards, technologies, and architectures that carry AI into the future.

Join the Ethernet Alliance as we chart the next evolution of Ethernet for AI.

Topics of Interest

The Ethernet Alliance's Technology Exploration Forum is a unique opportunity for individuals to present and share their ideas with members of the Ethernet community interested in exploring the future of Ethernet. Potential topics for discussion and presentations include but are not limited to:

- AI Networks Market Forecast
- Next-generation scale-up, scale-out, and scale-across architectures
- The Need for Beyond 1.6 Tb/s Ethernet
- The Consequences of the Physical Layer on the AI Network Stack
- Future Requirements of Network Equipment Targeting AI Use Cases
- Future Requirements of Compute Equipment Targeting AI Use Cases
- Latency requirements of AI Networks
- Advanced modulations for 400 Gb/s electrical signaling
- Developments in Copper Interconnect / Packaging Targeting 400 Gb/s
- Developments in Optical Interconnect/Packaging Targeting 400 Gb/s
- FEC / Coding Approaches
- The future of optical fiber
- Power & Cooling Considerations
- Testing & methodologies

Your Participation

The Technology Exploration Forum is open to the Ethernet community. Please submit the following information for your proposal for a panel or presentation.

Proposal Format (one page):

- ✓ Title
- ✓ Abstract
- ✓ Short biography of the presenter & contact information (job title, address, telephone, email)

Please note proposals for product overviews or marketing will not be accepted. All proposals should be emailed to TEF@ethernetalliance.org no later than **June 03, 2026**.

All proposals will be reviewed, and acceptance notifications will be provided on **July 1, 2026**. Panels based on complementary proposals may be organized.

Intended Audience

- Chief Technologists
- Hyperscale Data Center Architects
- AI Network Experts
- Compute and Network Architects
- System Engineers
- Packaging Engineers
- Electrical Signaling Integrity Experts
- Optical Signaling Experts
- DSP Engineers
- Electrical / Optical Component Engineers
- Interconnect Providers
- Optical Module Manufacturers
- Networking Marketing
- Solution providers & consultants
- Data Center Power Engineers
- Physical Layer Test Engineers
- Design Software Experts
- Network Performance Measurement Engineers

Sponsorship Opportunities

Does your company want to sponsor one of the biggest Ethernet events of 2026? Now you can! The Ethernet Alliance is offering multiple different sponsorship opportunities for those companies looking to get involved in the “Ethernet Intelligence” TEF. If your company is interested in being a sponsor, you can view the [sponsorship opportunities here](#) or contact morgan@ethernetalliance.org.

Contact Information

Email TEF@ethernetalliance.org

c/o Ethernet Alliance | 3855 SW 153rd Drive | Beaverton, OR 97006 | 503.619.0564